Project

Advanced Autocorrelator Technology

ESTEC Contract: 11211/94/NL/CN/CCN4

Title

Final report

Abstract

This report describes a spectrometer implemented in Multi Chip Module technology, i.e. two naked ASIC’s mounted on one carrier. A matter of fact, two different MCM’s has been developed, one focusing on wide bandwidth, low resolution applications, and one intended for higher resolution applications. The function has been demonstrated in lab tests, as well as by operating a full demonstrator spectrometer in a ground based 110 GHz radiometer.

The specification was 1 GHz bandwidth with 64 and 1024 spectral channels, and with a power consumption of less than 1 mW/GHz/channel. The result has been 1.7 GHz bandwidth, 128 and 1024 channels resolution, and 0.5 mW/GHz/channel power consumption.

The design, test results as well as application candidates are described in the report.
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List of Abbreviations

AOS  Acousto Optical Spectrometer
ACS  AutoCorrelation Spectrometer
ADC  Analogue to Digital Converter
ASIC Application Specific Integrated Circuit
CMOS Complementary Metal Oxide Semiconductor
CCD Charge Coupled Device
CSP  Chip Scale Packaging
CTS  Chirp Transform Spectrometer
DRC  Design Rule Check
DRDP Design Review Data Package
DSP  Digital Signal Processing
ERC  Electrical Rule Check
LVS  Layout Versus Schematic Check
MCM Multi Chip Module
MCM-L MCM based on high density laminated PCB
MPW Multi Project Wafer
PCB Printed Circuit Board
RTL  Register Transfer Level
S&H  Sample and Hold
SNSB Swedish National Space Board
SSC  Swedish Space Corp.
SOW  Statement Of Work
TBC  To Be Confirmed
TBD  To Be Defined
TDM  Time Division Multiplexing
VHDL VHSIC Hardware Description Language
VHSIC Very High Speed Integrated Circuit
VLSI Very Large Scale Integration
WP  Work Package
WPD Work Package Description
1. Introduction and Spectrometer Background

1.1 Overview

This report describes an autocorrelation spectrometer implemented in Multi Chip Module technology. A matter of fact, two different MCM’s has been developed, one focusing on wide bandwidth, low resolution applications, and one intended for higher resolution applications. The function has been demonstrated in lab tests, as well as by operating a full demonstrator spectrometer in a ground based 110 GHz radiometer.

The integration of quantizer and correlators into a single chip originally foreseen in this activity has proven to be unfeasible due to technological constraints, and it has been replaced by a Multi Chip Module (MCM) implementation. It has further been decided to investigate another way of improving the speed/volume ratio, the Chip Scale Packaging (CSP).

The report starts with an introduction to spectrometers and an overview of the ACS technology. This is followed by a description of the ASIC designs and test result. Finally, the design, implementation and test results from a demonstration spectrometer is shown. In addition, results form radiation tests of the chips are described.

The specification was 1 GHz bandwidth with 64 and 1024 spectral channels, and with a power consumption of less than 1 mW/GHz/channel. The result has been 1.7 GHz bandwidth, 128 and 1024 channels resolution, and 0.5 mW/GHz/channel power consumption.

The design, test results as well as application candidates are described in the report.

1.2 Spectrometers

In many applications when a signal is analysed with high spectral resolution, sometimes in the order of ten to the power of six or higher, heterodyne receivers are employed. In signal to noise limited applications, such as limb sounding aeronomy, the system is often divided into a low noise "Front-End" and a spectrometer type "Back-End". Even if the noise level of the spectrometer is uncritical, it must be very efficient, i.e. a commercial swept filter spectral analyser, that process only one "channel" at a time, will not do. The special environment of a satellite will add additional constraining requirements on the design of a "Back-End" spectrometer, such as low power consumption, size and weight. Of course, the quality aspects, such as radiation tolerance, is also of outmost importance.

In its most general form, a spectrometer can be considered to be a device that receives an input signal, which is variable in time, and estimates its power spectral density. The estimate is given sampled at N equidistant frequency points, or channels, $f_0,..., f_{N-1}$, separated in frequency by $B/(N-1)$, where $B$ is the bandwidth of the signal. Critical parameters are the total bandwidth, the transfer function of each channel, $H(f)$, and the stability of the spectrometer. Perhaps most important is that the spectrometer should add as little noise as possible to the overall system noise budget.

The most widely used spectrometers in aeronomy and radio astronomy are; the Chirp Transform Spectrometer (CTS), the Acousto-Optical Spectrometer (AOS), the Autocorrelation Spectrometer (ACS) and the Filterbank Spectrometer. Spectrometers based on all types of technology, except the Autocorrelation...
type, must be designed with fixed bandwidth and resolution, i.e. they are very inflexible for different kinds of observations. The Autocorrelation Spectrometer is in this regard flexible, but has previously suffered from a comparably high power consumption when processing very wide bandwidths. Due to development over the last 5-7 years, the autocorrelation spectrometer can today, in many cases, beat the alternatives with an order of magnitude in this respect.

The CTS is based on a chirp filter, that is used for a convolution process to transform the spectra from the time domain to the frequency domain. The chirp filter sets the bandwidth and resolution limits of a particular spectrometer, and 200 MHz bandwidth has been the upper limit for some time. In addition to the chirp filter, a chirp pulse circuit is needed, as well as a fast and accurate sampling and accumulation function. Access to a chirp filter compliant with the spectrometer requirements is the limiting factor for a CTS.

The AOS is based on a Bragg cell, where the signal to be analysed is feed acoustically in one end of the device. A laser is focused on the cell, and the light is deflected according to the spectral density of the signal. This is captured with a CCD. The Bragg cell sets the bandwidth and resolution limits of a particular spectrometer. In addition, some optics is needed for handling the light beam processing. From quality aspects, we have several critical parts in an AOS; the laser, the Bragg cell, the CCD and the optics.

In the autocorrelation section the main processing and detection is done in the time domain. This has many advantages, one being that the signal can be digitized with very low precision without losing very much sensitivity, and high speed digital electronics can be used for the processing with all the advantages of stability and system integration. State of the art autocorrelators use two-bit precision with about 90% efficiency.
1.3 Autocorrelation spectrometers examples

The autocorrelation spectrometer is one of four types of spectrometers being considered for space based (sub)millimetre heterodyne systems. The advantages of the digital autocorrelation spectrometer compared to Chirp Transform, Acousto Optical and Filterbank spectrometers are; stability, compactness, high reliability and variability in bandwidth and resolution.

1.3.1 ODIN SPECTROMETER

The ODIN satellite is a joint aeronomy and astronomy mission. The main payload consists of four tunable heterodyne schottky receivers in the frequency range 480-570 GHz and one fixed tuned 119 GHz heterodyne system. In addition, there is an UV-spectrometer.

There are four back-end spectrometers connected to the five heterodyne systems, two autocorrelation spectrometers, one AOS and one filterbank. The autocorrelation spectrometer and AOS power consumption are the same, while the size and mass of the AOS is 7 times the correlation spectrometer. The filterbank only consumes 2 W.

The ODIN satellite has been in successful operation for more than 2 years, the design lifetime, and a decision has been made to operate for an additional 2 years. The benefits of the variable bandwidth and resolution has been essential.

![FIGURE 1.2 The ODIN spectrometer core with 100-800 MHz bandwidth in steps with 0.13-1.1 MHz resolution. Other specifications are: 1 kg, 220x180x30 mm and 18 W power consumption.]

1.3.2 DLR/TELIS SPECTROMETERS

Based on a chip-set developed during 1998-1999, motivated by MASTER and FIRST, 600 MHz coverage and 256 channels resolution is possible with only two chips, one quantiser and one correlator chip. This can be used for compact spectrometers as well as more wideband alternatives. Master is an ESA instrument/mission concept for Earth Observation, while FIRST has been renamed Herschel, and is a submillimeter science mission.
A "standard" spectrometer with 2 x 2 GHz bandwidth, and 2 x 1024 channels has been designed, and two have been ordered for the DLR TELIS project, based on the chip set running at 500 MHz. TELIS is a balloon borne mission with three cryogenic submillimeter receiver front-ends. The spectrometers will be shared between the front-ends, through an IF processor, also designed and delivered by Omnisys.

This is now the standard spectrometer design available from Omnisys, with many possible configurations, and a $100K for a standard (not space level) implementation.

If we compare with available alternatives to achieve 4 GHz total processing bandwidth, we would need 2-4 AOS systems, with mass and power consumption in the 10 kg and 50 W class.

FIGURE 1.3 The current generation of spectrometers, with top and bottom views, based on a 256 channel correlator chip and digitizer with 1200 MHz effective sample rate. The box incorporates 2048 channels and configured with 2 x 2 GHz etc.

1.3.3 CURRENT DEMONSTRATOR

A new chip set has been developed under this contract, with one digitiser and two correlator chips. The digitizer has up to 4 GHz bandwidth, and the two correlator chips close to 2 GHz. One of the chips has 128 spectral channels, while the other one has 1024.

The number of channels used can be controlled to save power consumption, and the sampling rate can easily be changed by a factor of 1, 2, 4, 8.

To demonstrate the capabilities, a demonstrator has been designed and tested. The specification for the demonstrator has followed the Master / Marshal requirements, with 20 W power consumption and 10 kg mass. Master is an ESA instrument/mission concept and Marshal a prototype/demonstrator for this mission. The demonstrator has shown that the performance can be realised with a system of less than 1 kg and less than 8 W power consumption. With flight development, the mass could easily be reduced by a factor of two.
One demonstrator has been tested with an 110 GHz ozone radiometer in Bremen, using four correlator modules, proving the chip set's potential:

- 12 GHz bandwidth (6 GHz implemented in the demonstrator, space available for 12 GHz implementation)
- 1024 channels (512 channels implemented in the demonstrator, space available for 1024 GHz implementation)
- 110x170x30 mm / 800 grams
- 8 Watt

The correlator module is very compact, and can easily be incorporated in many low mass applications.


1.3.4 Correlator development

In the table below, examples of the chip development the last decade is shown. Major items of course bandwidth and system integration level, but for space applications, the power consumption is vital. From this table, it is clear that the Omnisys chip set.

<table>
<thead>
<tr>
<th>TABLE 1.1 Correlator chip sets</th>
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<tbody>
<tr>
<td>mW</td>
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<td>Bos</td>
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<td>Omnisys-ODIN</td>
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<tr>
<td>Omnisys&amp;ESA</td>
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<td>French HiFi</td>
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<td>Omnisys&amp;ESA: S</td>
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<tr>
<td>Spaceborne</td>
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<td>Omnisys SCS</td>
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Now, the chip set is not of interest to the scientist, and not to the system engineer or project manager either, it is the system performance and cost. For this we must look at the specification one step higher, the system level. For the proposal to the HIFI team for Herschel, the Omnisys alternative was 2 kg / 45 W, compared with the competitor’s 14 kg / 240 W. (The performance was comparable, and the redundancy cleaner for the Omnisys proposal). As the system difference can not only be explained by the chip power consumption difference, this exemplifies that focus on system design is essential. In addition, the Omnisys proposal was based on using packaged correlator chip’s, while the competitor’s was based on complex and large MCM’s.

Now, as a result from the development at Omnisys described in this report, a general conclusion is that autocorrelation spectrometers are very competitive with other type of spectrometers for space and ground based (sub)millimeter radiometry. The main advantages are: compact implementations, scalability and versatility in bandwidth and resolution, combined with potentially very high stability.

In terms of size, the correlator is clearly much more compact than either the Chirp or the AOS, an optimised CTS being 2-3 times the size of a correlator, while an AOS is at least 10 times larger.

In terms of power consumption, the CTS is comparable to the ACS for narrow bandwidth, while the AOS consumes 2-4 times more than the ACS for wide bandwidth applications. The CTS can not compete for wide bandwidth applications, while the AOS is not competitive for high resolution use.

In terms of flexibility in bandwidth and resolution, the CTS and the AOS have very limited capabilities.

The ACS uses no special technologies and components, such as lasers, CCD’s, Bragg Cell’s or Chirp filters, with concerns regarding availability, radiation tolerance and other quality concerns. The only special technology is the full custom design of the chip set, while a $1000 Billion industry helping in the production line set-up. The NRE for the ASIC’s are about $100-150 K. To this, qualification cost must be added, but in comparison with the ACS and AOS, no comparable qualification methods exists for Chirp filters, CCD’s, Lasers or Brag cells.

1.4 Project example: STEAM

1.4.1 Summary

The Stratosphere-Troposphere Exchange And climate Monitor (STEAM) project is technically feasible. The project addresses important goals for atmospheric scientists regarding climate research and the instrument technology needed is at hand, mainly through the previous Odin project. The project has the explicit support of research groups in at least three countries, and potentially in several other countries and in ESA. Since STEAM can build on methods and technology already developed for Odin, SMART-1 and other projects, the cost and risks should be lower than for Odin. Also, STEAM is in several ways a simpler system than Odin. The concept assumes daily operations to be conducted from SSC Esrange, near Kiruna.
1.4.2 Background and scope

In 1998 European scientists proposed to the ESA Explorer program a follow on mission to Odin named SCOPE (Stratospheric Chemistry Opportunity Explorer) similar to STEAM but without holographic capability. It was recommended by the evaluation committee but not selected. An advanced, imaging version of this instrument was proposed to CNES (MOST — Microwave Observations of Stratosphere and Troposphere) in 2001. The study demonstrated that the UT/LS part of the payload could fly as a microsatellite payload. STEAM was proposed in response to the SNSB call for ideas in 2002 and in the summer SSC was awarded a contract for a technical feasibility study of the Stratosphere- Troposphere Exchange And climate Monitor (STEAM) project. The study is aimed at defining at least one possible system configuration that would fulfil the scientific objectives of the project and estimating its cost and schedule. Included in the study was a smaller part aiming at identifying possible Swedish contributions to a French instrument for sounding the Mars atmosphere, MAMBO. The MAMBO part should address development status, synergy with the STEAM radiometer development and cost of the contributed hardware. Since the French Mars-probe Premier project was discontinued, less effort was spent in the study on the possible synergy between the two radiometers.

An important part of the study was directed to Omnisys Instruments, as subcontractor to SSC, for studying key parts of the radiometer equipment. The results of the study are summarised in the following.

1.4.3 STEAM scientific motivation

In summary, STEAM is dedicated to the investigation of chemical, dynamical, and radiative processes in the upper troposphere and lower stratosphere (UT/LS) altitude range and their links with the Earth climate and stratosphere evolution. The main objective is to provide vertically and horizontally resolved information on the global distributions of UT/LS key species such as water vapour (H2O), ozone (O3), and carbon monoxide (CO), and global fields of O3, H2O and halogen compounds responsible for the O3 destruction like chlorine monoxide (ClO) in the stratosphere. The UT/LS region plays an important role in the Earth’s climate system. Despite its importance there is still a lack of accurate, heightresolved data in the UT/LS. Confronting 3-D climate and chemical-transport models with STEAM observations will improve our knowledge on this critical atmospheric region.

Furthermore it is of vital importance to monitor on a global scale the evolution of the stratosphere beyond 2007 in order to quantify the expected decline of halogen compounds and check whether the ozone layer is starting to recover.

Radiative aspects will in particular be addressed by the measurements of H2O, O3, and N2O. Well resolved STEAM data of H2O, O3, CO, N2O, and CH3Cl in the UT/LS will allow studying dynamical processes such as stratosphere-troposphere exchange or transport between high-, middle and low-latitudes. Chemical aspects cover both the upper troposphere (O3budget, biomass burning, aircraft impact) and the lower stratosphere (ozone evolution) and will be investigated using the global dataset of H2O, O3, CO, N2O, HNO3, HCN, and CH3CN.

Thus, the three main research areas are climate evolution, stratosphere-troposphere exchange, and ozone in the troposphere and stratosphere. STEAM is supported by French, Swedish and Canadian laboratories, gathering the tropospheric and stratospheric science communities in these countries. It should also be noted that the scientific objectives cover at large part of the objectives of the ACECHEM project, proposed to ESA. ACECHEM was proposed by aeronomers of 13 institutes in 7 countries. It was highly rated for scientific merit but was not chosen for further studies within the ESA framework due to an estimated excessive cost. Thus, several other countries and ESA can be considered potential partners in the STEAM project, at least from a scientific-interest point of view, yet we have to reduce cost.

1.4.4 Payload

The main instrument on STEAM shall be a radiometer for mm and submm wavelengths, complemented by an optical instrument, partly similar to OSIRIS on Odin. The radiometer shall operate in the 320-360 GHz range to sound the UT/LS and in the 485-505 GHz range to sound the stratosphere. Using a unique technique for sounding the Earth atmosphere’s limb from 5 to 28 km by employing 8 simultaneous measurements,
STEAM shall produce a global data set of UT/LS key species with both a good vertical (1.5-2.5 km) and a good horizontal resolution (30-50 km). The mm band shall have the same line-of-sight as the optical instrument, which shall measure aerosols and clouds. The submm band shall cover 15 to 40 km in altitude, also with 8 simultaneous measurements. For the mm band the spectrometers shall have a maximum instantaneous bandwidth of 8 GHz at a resolution of 10-20 MHz. For the submm band the bandwidth shall be 4 GHz (2 GHz processed) and the resolution 2 MHz.

1.4.5 Radiometer concept

The telescope views thermal emission from the atmospheric limb imaged by a small linear array of heterodyne receivers in the instrument platform. The incoming radiation is down converted and amplified in the receivers. Spectrometers measure the spectral power density across each band, and digitised outputs are sent via the data interface to the spacecraft system to be eventually made available for ground processing.

The radiometer design is basically a simplified Odin design. Compared to Odin we do not foresee a need for power demanding active cooling, frequency tuning, single sideband operation and fundamentally pumped mixers. This makes it possible to build a simplified system with mixers directly fed by the telescope and pumped via wave-guides. It is then possible to build a multi-beam system and use novel tomographic methods to overcome one major limitation of the current limb scanning technique — the poor horizontal resolution. The telescope surface accuracy can be relaxed by a factor of 2 compared to Odin.

The telescope would be built and tested using the now proven Odin methods and would be an off axis Gregorian design with an elliptical (1 m × 0.5 m) main reflector constructed of carbon fibre composite (CFRP) for thermal stability. Its support structure could be built in the shape of a CFRP box that also houses the optics, calibration sources, LO units with phase lock electronics and the mixer assemblies.

There will be optics to provide means for calibration and for switching towards cold space. In this modified Odin scheme the receiver signals are separated by means of a polarising grid, creating two sets of 4 beams. Further separation is achieved by imaging the focal plane onto the set of mixer horns. All eight receivers thus receive the signal from different parts of the limb simultaneously. A mesh filter can be included to suppress higher harmonics of the sub-harmonically pumped Shottky mixers. HEMT based low-noise amplifiers mounted next to the mixers will provide the first amplification. With InP-Gunn oscillators there is sufficient power for one LO to pump four mixers. The units would be phase locked, using almost the identical design to Odin’s. They would drive either a Varactor or the Gunn voltage to correct for the error signal determined by comparing the harmonic from the 86 GHz range to an internal reference source locked to a stable low frequency clock source. LO chain designs based on multipliers and power amplifiers is also an alternative, and this is under development at Omnisys and will be demonstrated during Q1 of 2004. The backends are required to select and process the frequency regions surrounding the molecular lines of interest, synchronised to instrument pointing and reference switching. Autocorrelator spectrometers will be used as backends. The autocorrelator, being a digital processor, is well adapted to space use and is inherently stable. ESA has within the technology research program developed, for future limb scanning missions, a more modern and in many ways improved correlator chip compared to the Odin design. In the case of a limited power budget, one could use a reduced number of autocorrelators for the bands, where the mixer outputs are time-multiplexed to the backends. However, this would compromise sensitivity and/or spatial resolution. These tradeoffs require further investigation.

1.4.6 Radiometer overview

The baseline system design for STEAM is to cover several atmospheric lines of interest, split on two main frequency bands, 320-360 GHz and 495-503 GHz. This requires two sets of front end receivers, and that the 320-360 GHz is tuneable.

The baseline is also to utilise linear arrays of receivers to cover different altitudes in parallel, simplifying mechanics as well as increasing the efficiency. This is planned to be implemented with two sets of four receivers for each band, the two arrays working with different polarisation, for minimum sampling distance.
FIGURE 1.6 Steam radiometer system overview.

These four arrays of four receivers need access to the sky with four horns, the IF outputs of 4 times 8 GHz (6-14 GHz TBD), as well as LO to all receivers.

The output from the IF amplifiers are then feed to an IF system, followed by spectrometers. The LO (and biasing) will be provided as by a Front-end Control system.

Main characteristics
- Multibeam (simplified optics) and developed as an integrated instrument
- 8 front-ends at 320-360 GHz, DSB (simplified optics)
- 8 front-ends at 490-505 GHz, DSB (simplified optics)
- 8x8 GHz + 8x4 GHz = 96 GHz of spectrometers
- operation in ambient temperature (simplified system) with 2000 K Tsys (prel)
- a few kgs, 60-70 W total payload power consumption.
- on-board, near real-time signal processing (Linux)

1.5 Example 2: MAMBO

The MAMBO (Mars Atmosphere Microwave Brightness Observer) instrument was intended for the French-led mission to Mars, PREMIER, later cancelled due to financial problems. This would have been the first time the atmosphere on another planet had been investigated in detail. There was both scientific, data processing and technical overlap between STEAM and MAMBO. The MAMBO receiver is basically a single channel STEAM receiver but requires higher spectral resolution due to the low pressure on Mars. Both have the same requirements for high bandwidth to covering the somewhat widely spaced spectral lines. There were substantial synergy effects between the instruments. For instance, it would be possible to use a STEAM mixer block with its local oscillator and phase lock system unchanged for MAMBO.

Compared to the old MAMBO design, partly based on traditional hardware from space industry and from JPL, both size, mass and power can be substantially reduced. Based on the investigations made so far, it is proposed to carry out a feasibility study (“Phase 0”) regarding the possibility to build a Swedish low-cost, low-weight alternative to the MAMBO instrument. This instrument could be accommodated on a Mars micro probe, proposed within another study for SNSB (Swedish National Space Board) as one of the
alternatives for a technology research satellite (“Tsat-Mars”).

1.5.1 SCIENTIFIC OBJECTIVES

The microwave sounder MAMBO aims to characterize the dynamics and the composition of the Martian atmosphere, with an unprecedented sensitivity. For this purpose, MAMBO will analyse the thermal emission of the atmosphere at microwave frequencies using heterodyne spectroscopy, for the first time from orbit around another planet.

In practice, MAMBO will perform measurements at the atmospheric limb and at nadir using a receiver dedicated to the monitoring of selected lines of key molecules in the range 320-350 GHz:

- CO at 345.796 GHz
- 13CO at 330.588 GHz
- H2O at 325.153 GHz
- HDO at 335.395 GHz
- O3 at 326.901 GHz
- H2O2 at 326.981 GHz

1.5.2 Radiometer concept

The radiometer concept is based on two identical subsystems, both covering the frequency band of interest, as shown below.
The basic idea is to have redundancy, and with both systems operating, we have an improved system performance by an effective reduced system noise temperature with a square root of two.

There are several advantages of using an ACS compared with CTS, that also has been considered. The main aspect is the flexibility in bandwidth and resolution, but also the wide bandwidth possibilities of a modern ACS. From system level perspective, this reduce the mass and power consumption with at least a factor of four.

1.5.3 Specific physical objectives

The instrument performances will allow the 3D mapping, with an excellent spatial cover, of the following physical items:

Wind:

The MAMBO high spatial resolution allows to make use of the line profiles and their Doppler shift. Limb viewing allows a direct measurement of the winds on Mars from orbit. Both 13CO and CO will be used to monitor the atmosphere from 20 km to 130 km, with a vertical resolution better than 10 km and an 10 m.s⁻¹-accuracy.

Temperature:

From the planet surface up to 120 km. The temperature profile will be retrieved from CO and 13CO lines. This will allow an unprecedented accuracy, especially during periods when the atmosphere is dust laden.

Water Vapour:

Using the H2O and HDO lines will allow measuring water vapour profiles from near the surface up to 60 km, with an accuracy and a sensitivity much better than previous experiments.

D/H Ratio:

This isotopic ratio will be obtained by simultaneous spectroscopy of H2O and HDO. Monitoring D/H ratio is a key investigation to understand the evolution of water on Mars.

Ozone:

Ozone profile will be measured accurately up to 70 km, simultaneously with water vapour. This will allow us
to better understand the relationship between the two species. Ozone and Water vapour are supposed to anti-
correlated.

**Hydrogen Peroxyde (H2O2):**

This species has never been observed on Mars, yet. Several models have shown its key importance for the
photo-chemistry of the Martian atmosphere (control of H2, O2 and CO) and for its role in oxydizing the
Martian soil, a key issue for exobiology.

**Carbon Monoxyde:**

The observation of the strong 12CO line simultaneously with the weaker 13CO line will allow to estimate
CO vertical profile with an accuracy of 10-15% up to 90 km in limb viewing.

**Surface Science:**

Careful analysis of the brightness temperature will thus allow the mapping of the variations of surface
emissivity e and possibly the thermal inertia of the subsurface.

### 1.5.4 Global objectives

**Atmospheric dynamics and comparative meteorology:**

The simultaneous knowledge of the zonal wind and of the thermal structure of the atmosphere combined
with state-of-the-art techniques of data assimilation in General Circulation Models will allow us to determine
the 3D atmospheric circulation day after day.

**Water cycle:**

In combination with the observation of the General Circulation, the 3D mapping of water vapour should
allow us to characterize water vapour transport by the atmosphere and locate its sources and sinks.

**A global view of Martian atmosphere photo-chemistry**

H2O, O3, H2O2 and CO are key species for the photochemical equilibrium of the Martian atmosphere and
its interaction with the surface. The observations of the temporal and spatial variations of these species will
be interpreted in light of a 3D photochemical model, allowing a true understanding of the processes involved
and their coupling.

![FIGURE 1.9 Scanning.](image)

### 1.5.5 MAMBO Operating Modes Description

When MAMBO is fully operating (beside OFF, stand-by, TM/TC modes), MAMBO will combine several
modes of observation in which be operated in four main modes. MAMBO antenna will alternately look at:

1. One or several points between Nadir and Nadir±70° (integration time per point: 1 - 5 s)
2. The limb on one side (see details below)
3. The cold calibration target (cold sky above the limb)
4. The internal calibration hot load
MAMBO will repeat the same operations on the other side (modes baseline) or on the same side (in some specific operating modes).

The observing strategy at the limb is a key issue. A few inputs regarding the limb strategy are:

MAMBO antenna will rotate preferentially step by step. A constant angular rate would be considered if it is shown to strongly simplify design considerations.

MAMBO will acquire one spectrum every 5 km (limb vertical projection).

The angular rate of the antenna will be suited to a limb scanning velocity of $3 \pm 2$ km/s. The corresponding angular rotation rates is given in the table below.

Limb scanning shall be performed in the range 0 km to 120±10 km. Margins are required on both sides of this scale depending on the strategy fostered to identify the limb / surface border on the basis of the information provided by the orbiter main CPU and/or from the detection of the limb by the instrument itself.

FIGURE 1.10 Limb scanning.
2 Autocorrelation Spectrometer Background

2.1 General ACS Architecture

In a digital autocorrelation spectrometer core, the signal is first translated and conditioned in a few analog processing steps before the digitizing and correlation.

![Autocorrelation spectrometer](image)

**FIGURE 2.1 Autocorrelation spectrometer.**

The digitized signal is delayed in a number of discrete steps, and the delayed samples are multiplied with an undelayed version of the same signal. The products from the multiplications are then integrated and accumulated separately for each of the delay stages. After a specified integration period, usually of the order of seconds, the autocorrelation function is transformed to the frequency domain to form the power spectrum. The autocorrelation spectrometer is based on Wiener-Khintchines theorem:

\[
S(\omega) = \int R(\tau) e^{j\omega \tau} d\tau
\]

where

- \( S(\omega) \) = power spectrum
- \( R(\tau) \) = autocorrelation function

This is the theoretical foundation of the autocorrelation spectrometer, but the digital implementation differs in a number of points from the equations outlined above. The main differences are

- (i) the data is discrete in time
- (ii) the data is discrete in amplitude and very coarse
- (iii) the data set is finite
- (iv) reduced total power dynamic range

Point (i) is taken care of by the Nyquist criteria, i.e., as long as we sample with a rate twice the input bandwidth or higher, the sampled values contains all the spectral information. In reality, the signal is sampled at a slightly higher rate to accommodate the finite slope of the filter preceding the digitizer.

That the data is sampled with very coarse accuracy, usually with one or two bit precision, has two implications. The major is that the signal to noise ratio is degraded, but for a 1.5-bit autocorrelator, the degraded efficiency is still better than 90%, and can be compensated by using a slightly longer integration time. While the theoretical degradation is listed in Table 2.1., as a function of number of bits used, the actual degradation depends also other factors, such as the statistics of the input signal. The other implication is that the correlation estimate is biased, but this is easily taken care of in the processing steps preceding the Fourier-transform.

The coarse quantization reduces the sensitivity but it also creates new spectral components [Van Vleck&Middleton 1966]. These effects are actually one and the same: the spectral power "leaks" from the original band and creates the new features. The well known effect that sampling at a frequency higher than the one specified by the Nyquist criteria increases the sensitivity results from the fact that some part of the leaked power is also covered in the processed band.

The reduced dynamic range only applies to the total power variations, not the peak power in one channel and is usually not a problem. The practical total power dynamic range is 2-3 dB for a fixed system for a reduced sensitivity of less than 2%, however, various gain adjustment features are commonly used providing 10-20
dB total power dynamic range or more. Both attenuators and variable gain amplifiers as well as adjustable ADC reference levels can be used.

## 2.2 Correlator Chip Architectures Time and Frequency Multiplexing

For the overall architecture, we have various design choices to achieve wide bandwidth. In Figure 2.2, a straightforward autocorrelation spectrometer is shown. It consists of a filter with 1.2 GHz bandwidth, an ADC operating at 2.6 GHz and a 32 channel autocorrelation block, also operating at 2.6 GHz. The resulting spectrum would consist of 1.2 GHz wide band divided into 32 spectral channels.

**FIGURE 2.2** A straightforward autocorrelation spectrometer. The 2.6 GHz sampling rate is chosen to be twice the input bandwidth plus a small oversampling factor to accommodate the finite slope of the filter.

In Figure 2.3, a frequency multiplexed (or sometimes referred to as hybrid) autocorrelation spectrometer is shown. It consists of two 600 MHz wide filters, two ADC’s working at 1.3 GHz clockrate, each attached to a 16 channel autocorrelation block, also operating at 1.3 GHz. The resulting spectrum would consist of 1.2 GHz wide band divided into 32 spectral channels.

**FIGURE 2.3** A frequency multiplexed autocorrelation spectrometer. The 2.6 GHz sampling rate is chosen to be twice the input bandwidth plus a small oversampling factor to accommodate the finite slope of the filter.

In Figure 2.4, a time multiplexed autocorrelation spectrometer is shown.

**FIGURE 2.4** A time multiplexed autocorrelation spectrometer. The 2.6 GHz sampling rate is chosen to be twice the input bandwidth plus a small oversampling factor to accommodate the finite slope of the filter.

It consist of filter with 1.2 GHz bandwidth, an ADC operating at 2.6 GHz, a serial to parallel converter with two output data streams at 1.3 GHz clockrate. These two data stream feed two 16 channel autocorrelation block, also operating at 1.3 GHz. The resulting spectrum would consist of 1.2 GHz wide band divided into 32 spectral channels. The overhead to accommodate time multiplexing is small if the number of channels in each bank is kept sufficiently high, i.e. 16-32 or higher.

The frequency and time multiplexing approaches can be combined, and a design choice depends on available technologies, size and power constraints as well as functional specification. The major trade-off between
time multiplexed and frequency multiplexed designs can be for power consumption. The frequency multiplexed design can help to reduce the power consumption for wide bandwidths.

There are four alternative architectures if we include the combination of a time multiplexed and frequency multiplexed design. We can summarize the major the advantages/disadvantages as:

- **Straightforward**: best choice if the bandwidth and power consumption can be accommodated with both the ADC and the correlator section clocked at a frequency of twice the processed bandwidth.
- **Frequency multiplexed**: best choice if neither the ADC nor the correlator can be implemented with the specified bandwidth, or if the power consumption is too high. It is not as amplitude stable as the other two methods.
- **Time multiplexed**: best choice if the ADC but not the correlator can be efficiently implemented with a clock rate of twice the input bandwidth

### 2.2.1 Hybrid spectrometer signal processing (frequency multiplexed)

The different processing steps in an autocorrelation based hybrid spectrometer are described below, starting with the hardware section, i.e. filtering, mixing, digitising and correlation. This is then followed by the software section where the data is corrected for the digitizer effects, Fourier transformed and, if a hybrid approach is used, the subspectra are joined to form a continuous spectrum.

Let us denote the spectrum of the input signal \( s \) by

\[
S_m(\omega),
\]

where \( S \) is an ergodic signal with slightly filtered white noise characteristics. After the analogue processing, i.e., filtering, mixing and gain adjustment, we get

\[
S_1(\omega) = S_m(\omega) F_1(\omega), S_m(\omega) = S_m(\omega) F_m(\omega), \ldots, S_M(\omega) = S_m(\omega) F_M(\omega)
\]

where the signal is split up in \( M \) frequency subbands, \( S_m(\omega) \), by the filter functions \( F_m(\omega) \). \( M \) equals unity if a none hybrid approach is used. Each signal is then quantized and multiplied by a delayed version of itself to form an autocorrelation estimate. As the autocorrelation function is defined in the time domain, the following two stages are treated in that domain, where the analogue and digitized representation of \( S_m(\omega) \) are denoted \( s_m(t) \) and \( z_m(nT) \), respectively.

![FIGURE 2.5](image)

**FIGURE 2.5** Hardware based processing in a hybrid spectrometer.

The digitization process consists of two parts: sampling of the signal at discrete time intervals, \( t = nT \), and quantization of the amplitude. The quantization function \( q(x) \) for a 2-bit correlator is described in Figure 2.2.

After the digitization, we have the autocorrelation estimate \( r(kT) \) formed by the function

\[
r_m(kT) = \frac{1}{N-1} \sum_{n=0}^{N-1} z_m(nT) z_m(nT + kT)
\]

where \( kT \) is the delay. \( N \) is usually a very large number and the number of delay lags range from a few to a
In the hybrid spectrometer, the software plays as important a role as the hardware. The data is accumulated in the time domain as autocorrelation functions and the data must be transformed to the frequency domain. Known instrumental effects should also be removed. However, all processing steps could be performed either on-board or at a later stage on ground.

The readout autocorrelation estimate stored in the lag registers has systematic, but known errors, and cannot be used directly. The first stage of the software processing is to translate the quantized autocorrelation function, \( r_m(kT) \), into a normalized analogue one with as little bias as possible. The operator, Q, which is derived in [Emrich 1992], takes care of this process. The corrected autocorrelation function is

\[
r'_m(kT) = Q[r_m(kT)]
\]

The quantization correction cannot be expressed in a simple equation. The correction is dependent on the threshold and shown above, the function is plotted for two different values. The correction is specific for this type of correlator and is dependent on the relative threshold level \( v_0 / \sigma \) (relative compared to the input rms voltage). Because the quantization correction is not a simple equation, it is normally implemented with a polynomial fit. As the quantisation correction is performed on ground, a high order polynomial can be used, however, for more compact code in an embedded system, the correction could be divided into 2-3 regions with 5-7 order polynomials used for each region.

This is followed by a Fourier transform and scaling with total power information derived from the zero lag or from a separate total power detector (see [Emrich 1992])

\[
S'_m(\omega) = p_m F[r'_m(kT)]
\]

where \( p_m \) is the total power estimate of each subspectrum and \( \omega_i \) indicates that the spectrum is sampled in discrete channels. The number of spectral channels is often chosen to equal the number of delay lags, but both fewer (smoothing) and more (interpolating) can be used. The autocorrelation function is both real and even, and the Fourier transformed spectrum is also real and even. Even if an FFT is sometimes used for the transform, the number of spectral channels will equal the number of autocorrelation channels. Depending on transform used, the input data must be manipulated to fulfill the even and real criteria, i.e., mirroring the data around zero to create the even data set for a cosine transform.

The continuous spectrum is obtained for hybrid spectrometers by joining or linking the subspectra. The possible implementations of the linking operator are discussed in [Emrich 1992]. A straightforward implementation is to sort the spectral "channels" by frequency and not use the "channels" where the subbands overlap.

We have now derived an unbiased estimate of the combined power spectrum at the filter outputs. To go further and remove the effects of filter and amplifier responses a differential measurement is used, i.e.,

\[
S'(\omega) \approx \frac{S_{on}'(\omega) - S_{off}'(\omega)}{S_{off}'(\omega)} = \frac{S*_{on}(\omega)F_{M}(\omega) - S*_{off}(\omega)F_{M}(\omega)}{S*_{off}(\omega)F_{M}(\omega)}
\]

where \( S^*(\omega) \) denotes the power spectrum with a "perfect" filter response and \( F_M(\omega) \) describes the combined filter effect of all components in the system preceding the digitizers. \( S^*_{off}(\omega) \) denotes a power spectrum estimated in the same way as \( S^*_{on}(\omega) \), but with the antenna pointing towards a clear sky instead of at the
source of interest. If $F_M(\omega)$ is constant with time and signal power is about the same between the on and off spectra, the filter response effects will be removed. Variations on the differential method can be used for other calibration procedures, such as hot/cold load methods, the concept is the same; measure the frequency response over the band and apply it to the uncalibrated spectrum. The differential measurement process also cancel to the first order the spectral distortions in the receiver front-end.

2.3 Real and Complex Downconversion

In the traditional autocorrelator design, the frequency band to observe is downconverted to baseband before analog to digital conversion. The translation can be implemented with either a chain of filters and mixers, or using a standard single sideband filter solution, as used for the ODIN spectrometer. The benefits of the SSB method is a reduction size as well as power consumption, but also some added flexibility, but the sideband rejection may be limited to some 25-27dB.

The subcircuits limiting this rejection is mainly the wideband phaseshifters needed, as shown in figure 2.7, but there exist alternatives. One of these is to perform a complex correlation instead, with the sideband separation in the post processing stage. Apart from removing circuitry, and the associated errors, this facilitates additional post processing clean-up, by measuring phase and amplitude mismatches.

![FIGURE 2.7 Real time and complex sampling implementations.](image)

In summary, the benefits of the complex sampling:

- The complex sampler does not require high quality single-sideband filtering (the matched 45 degree phase delays and summation block in Figure 2.12) of the analog input signal. This can significantly reduce the design effort when building a spectrometer.
- The complex sampling frequency is half the sampling frequency used by a real quantizer. The effective sampling frequency will remain the same, since twice as much data is produced per sample.

The complex sampling method has been chosen for the spectrometer chip set in this project.

2.4 Quantisation and Power Detection

The analog to digital converter should quantize the signal into a number of states, sample the signal in the time domain and encode the states into digital word. The order of these three stages may vary as well as the encoding scheme. As an example, the quantizer mapping function for a 1.5 bit and 2-bit correlator is shown in Figure 2.8.
FIGURE 2.8 The quantization function $q(x)$ for two bit converters to the left and for 1.5-bit converters to the right.

The ADC can be operated with a normalized signal level compared with the reference levels or used with a varying signal level. With an un-normalized signal, the zero-lag from the autocorrelation function can be used as a total power estimate. For a normalized operation, a separate total power detection scheme is needed.

The normalization can be implemented in two ways; adjusting the gain of the input signal, or adjusting the reference levels of the ADC. The latter has the advantage that non-symmetric errors could be compensated for, such as an offset in one comparator.

For wide bandwidth systems with a critical ADC specification, the use of a separate total power detector combined with an ADC output monitor relax the ADC specification in areas such as DC-drift and symmetry.

The total power detector could be based on an ordinary temperature compensated diode detector system, while the ADC monitor consist of counters, each monitoring the number of samples in each output state. This information would then be processed and used to adjust the ADC reference levels through a digital to analog converter (DAC). The adjustment can be made in real-time or as a part of a calibration procedure.

One of the main issues in the design of digital correlators is the quantization method chosen. If the signal is considered to consist of filtered white noise, a very coarse quantization give very little efficiency degradation.

The common model to calculate the degradation in efficiency, i.e. the derived noise floor after a fixed integration time compared to an ideal detector, is based on pure white noise with a time sample to time sample correlation of zero. The math involves a lot of work, but fortunately, this work has been done for us. From [Emrich 1992], [Cooper 1969] and [Hagan&Farley 1973], we can summarise a number of quantization methods and their efficiency factors, as shown in Table 2.1.

TABLE 2.1 Correlator quantization

<table>
<thead>
<tr>
<th>Method</th>
<th>Levels</th>
<th>Note</th>
<th>Efficiency</th>
<th>Gates and Power</th>
</tr>
</thead>
<tbody>
<tr>
<td>Multi$^*$ x Multi</td>
<td>N x N</td>
<td></td>
<td>1</td>
<td>1000</td>
</tr>
<tr>
<td>Multi x 1 bit</td>
<td>N x 1</td>
<td></td>
<td>0.8</td>
<td>100</td>
</tr>
<tr>
<td>Multi x 1.5 bit</td>
<td>N x 3</td>
<td></td>
<td>0.90</td>
<td>100</td>
</tr>
<tr>
<td>Multi x 2 bit</td>
<td>N x 4</td>
<td></td>
<td>0.93</td>
<td>100</td>
</tr>
<tr>
<td>1x1 bit</td>
<td>1x1</td>
<td></td>
<td>0.64</td>
<td>1</td>
</tr>
<tr>
<td>1x2 bit</td>
<td>1x4</td>
<td></td>
<td>0.75</td>
<td>2</td>
</tr>
<tr>
<td>1x1.5 bit</td>
<td>1x3</td>
<td></td>
<td>0.72</td>
<td>2</td>
</tr>
<tr>
<td>2x2 bit</td>
<td>4x4</td>
<td></td>
<td>0.88</td>
<td>6</td>
</tr>
<tr>
<td>1.5x1.5 bit</td>
<td>3x3</td>
<td></td>
<td>0.81</td>
<td>3</td>
</tr>
<tr>
<td>2x2 bit mod</td>
<td>4x4</td>
<td>reduced mult</td>
<td>0.88</td>
<td>5</td>
</tr>
<tr>
<td>2x1.5 bit</td>
<td>4x3</td>
<td></td>
<td>0.83</td>
<td>3.5</td>
</tr>
<tr>
<td>3x3 bit</td>
<td>8x8</td>
<td></td>
<td>0.96</td>
<td>9</td>
</tr>
<tr>
<td>2x2 bit red/os</td>
<td>4x4</td>
<td>reduced mult &amp; oversampling</td>
<td>0.93</td>
<td>3.5 x 2</td>
</tr>
</tbody>
</table>

$^*$) multi-bit implies a near infinite resolution. In practice 6-8 bits would suffice.

The efficiency factor can further be increased with oversampling the signal, i.e. increasing the correlation
factor. Most gain is achieved for coarse quantization, and in the table, the popular reduced multiplication scheme 2x2 bit is shown with an oversampling factor of two. The efficiency was increased from 0.88 to 0.93. It should be noted that these calculation are based on the simplification that the channel to channel correlation is zero, which actually gives low estimates for the real efficiency. For 1x1 bit correlators, the efficiency can be better than 0.7.

For 1.5-bit, Omnisys has measured between 85-93% efficiency, on the HIFI demonstrator Complex correlator design.

2.5 Correlator Chip Architectures

A correlator chip architecture can be made with a simple architecture. Two data streams should be multiplied with each other, one undelayed version of the signal and one that is delayed in a number of stages. The result should be accumulated for each delay stage.

The delay circuit could be implemented in two ways, a straightforward way with one delayed and one undelayed datapath in parallel, or with an xy-architecture. In the xy-architecture the data goes in two directions. For an autocorrelator, the data output from the end of the x-delay chain is fed to the y-input.

![FIGURE 2.9 Two different data flow architectures, the straightforward approach to the left and the xy-type to the right.](image)

In the straightforward implementation, the lag closest to the inputs is the zero-lag. This makes it simple to use variable length autocorrelation estimates (to save power) by shutting down the higher lags when not in use. The cascading of chips is also easier for the straightforward architecture. For the chips in this report, the major implication is that with the straightforward implementation, the design can be made asynchronous, with reduced power consumption and/or higher clock speed.

A very useful option is to incorporate a quantizer monitor; a device that measures the statistics of the input signal. This is a very simple device to implement, it just counts the number of samples in each state. To save chip area, one monitor channel can be time-shared between the four states as the monitoring process does not need to be continuous. A fifth state could also be useful, measuring time. In this way, the readout and accumulation of the integration time is performed in exactly the same way as with the correlator channels. The integration time is needed to normalize the raw autocorrelation data. This monitor is also a total power detector, and can be used as such in a frequency multiplexed spectrometer implementation.

![FIGURE 2.10 The architecture of an autocorrelator.](image)
The digital part can also use time sharing and parallel processing schemes to allow for a difference in input data rate and system clock rate. With a multiplexing factor of less than unity, let's say a factor of 1/4, a 256 MHz, 64 channel device is used as a 64 MHz, 256 channel one. With a time multiplexing factor of 4 instead, the device could be seen as a 1024 MHz, 16 channel device. Excluding the overhead, this device would consume the same amount of power in all three cases, i.e., a good quality measure is power consumption divided by number of channels times the sampling rate, $P_x = P_{cell} / (N_{ch} \times S_c)$. In practice, time multiplexing factors of less than unity usually lead to a large overhead and are seldom used, while factors of 2-8 are common to provide large bandwidths.
3 System Level Optimization

A complete spectrometer based on the autocorrelation principle needs:

- High frequency interface
- Downconversion to baseband
- Analog to digital quantisation
- Correlation
- Control and Power interfaces

At least the first and last parts are very similar for most kinds of spectrometers and it is important to keep this in mind while doing comparisons.

Most of the technical development and discussions during the last two decades has focused on just the Correlation section, but for the last decade, this is in many cases not totally dominating the power consumption, as is very often claimed.

![Figure 3.1 The main subsections in a digital spectrometer.](image)

For the ODIN spectrometer (1997 design), the following power consumption was achieved:

- High frequency interface (3.5-4.5 GHz, 6 ports, no frequency translation): 0.8 W
- Downconversion to baseband (four SSB converters): 3.2 W
- Analog to digital quantisation: 2 W
- Correlation: 3.2 W
- Control and Power: 6 W

Total = 15.2 W.

This was achieved through optimization in all parts, and for "Control and Power", 6 W was the result from some conservatism regarding CPU and PROM etc.

From this design, Omnisys has developed another type of topology, reducing the "Downconversion to baseband" circuitry and facilitating wider basebands. This needs design changes in the "Downconversion to baseband" part, in the "Analog to digital quantisation" and the "Correlation" part. For the two last ones, two generations of chip sets from Omnisys has facilitated this and even for the first part, a special integrated circuit is under development, although standard components can be used with slightly higher consumption.

For wide bandwidth applications, it is of great advantage to combine the "Analog to digital quantisation" and the "Correlation" in the same IC, reducing the interface power consumption.
3.1 High frequency parts

Depending on operating frequency, there are several possible technologies. With development starting at now, we could consider GaAs MMIC up to some 60 GHz operation, and 20 GHz is fairly straightforward. With lower IF frequencies, lets say below 10 GHz, SiGe with and without CMOS becomes of interest. In the latter case, a more integrated solution is possible and/or lower power versions.

The parts that are needed are:
- Mixers
- Amplifiers
- probably filters
- Oscillators

One of the major questions how you integrate the High frequency parts and the Low frequency parts, but lets say that with 20 GHz +, two subsystems may be needed, and with 10 GHz -, these should be totally integrated, if enough resources is spent on development.

3.2 Low frequency parts

The task for the low frequency part is to condition the signal before the "Analog to digital quantisation", i.e amplification, filtering etc. Traditionally, this has been based on microwave type design and components, but for the ODIN design, wide band opamps were used with a more RF/analog design technique, reducing problems with skew etc. in the signal interface between the different parts. In general, technologies focusing on "RF" is better for these task, than pure "microwave" components.

In terms of size, as well as manpower for "trimming", the low pass filters can not be neglected. With high frequencies, 1 GHz and above, and some time for development, thin film realisations seems the best choice.

3.3 Analog to digital quantisation (digitizer)

Traditionally these have been based on designs with "standard" components, such as comparator. To reduce power consumption and mass, for the ODIN project, a matched chip-set were designed, i.e. the "Analog to digital quantisation" IC was matched to the "Correlator" IC, in signal levels as well as pinout, facilitating the implementation of an MCM with 2 x 8 devices on 35x80 mm.

From this, it has become a standard for Omnisys to design such chip sets in parallel, were you have benefits in terms of size, power consumption as well as performance.

For most aeronomy applications, the "Analog to digital quantisation" IC will consume as much power as the "Correlator" IC, as state of the art is a few hundred milliwatts, and the interface power consumption could even dominate. The solution for this would be to combine "Analog to digital quantisation" and "Correlator" in one device, and luckily, technologies were this is possible for this has been developed for the consumer RF applications. Examples are advanced BiCMOS processes, based on SiGe, from IBM and others.

3.4 Correlator parts

As stated above, the next stage in development is to combine "Analog to digital quantisation" and "Correlator" in one device, which will need some trial and error effort. The implication of this is that the CMOS part will be one generation behind compared to pure CMOS, but as this may be optimum for many applications, as indicated above.

Projects starting today could be based on SiGe BiCMOS with 0.25 um CMOS part, while 0.18 and 0.13 is in the planning from many foundries. The SiGe/Bipolar part should have Ft starting at 60 GHz, i.e. analog to digital quantisation of some 5 GHz should be straightforward, and mixers in the 15-20 GHz range possible.

3.5 Power and control

For the power interface, we probably need several voltages on the inside, such as 1.8 V, 2.5 V, 3.3 V as well as 5 V. For a complete instrument, it could be optimum to operate non isolated from some "central"
radiometer power supply, starting at 12-15 V, or even 5 V. The radiometer will not be isolated anyway, in most implementations, as the microwave interfaces are not isolated, i.e. the spectrometer is connected to the warm IF amplifier, that is connected to the cold IF LNA etc., something that is often forgotten on high level.

For the control and data read-out, this can range from simple state machines in the correlator chips directly, to external ones (FPGA based), with or without advanced buffering, to be micro controller based. In the last case, the selection on quality is one of the most important questions, "commercial" solutions consuming tens of milliwatts exist, while with "space level" solutions, several watts are needed.

Omnisys has used both "state-machine" controlled spectrometers with FPGA's, as well as micro controller based ones with smart buffering, dynamic data reformatting etc.
4 Chip Scale Packaging (CSP)

4.1 Introduction

While traditional integrated circuit packages has become more and more a limiting factor in terms of performance in most high speed electronic systems, the possibility to remove package parasitics is accomplished by using naked die mounted in an MCM. But the use of MCM technology, that has been available for a long time, still has a lot of drawbacks. The most obvious one is the KNG (Known Good Die) issue which includes the problem of both testing the chips under realistic conditions as well as the problem of screening, burn-in etc.

During the last 3-5 years, the concept known as CSP (Chip Scale Packaging) has come up as a solution to these problems. The concept is to provide a package that increase the size of the naked die with only 30-50%, while traditional packages often are 1000% bigger than the die. In addition, the added parasitics will be an order of magnitude less than with most traditional packages.

The original project aimed for a single chip spectrometer, mounted in a CSP type of package. Now, the same type can also be used to house the two chips in the chip set designed in this project.

We have tested this concept on the chips previously produced, the 256 channel devices, which has been tested both as naked die and with a traditional Quad FlatPack. The baseline choice was to use to be some kind of Micro BGA type package.

![CSP from Abpac.](image)

The purpose of this work is not to qualify a CSP package, or not even to find a qualifiable design, but to find out the potential performance enhancements provided with this technology as well as size impact.

4.2 Technology choice

Early in the project, more than 20 companies were contacted regarding the manufacture of a custom CSP. There were detailed discussions with 6-7 companies, but the only CSP producer willing to give insight on the implementation, which was necessary for the project, were the company giving an offer to do the work before the project tender was submitted. This company went bankrupt a few weeks after the project was started.

This led to the investigation of alternatives, and it was decided after, discussions with M. Hollreiser, to design, manufacture and test an Omnisys full custom CSP instead. This was an increase in work load accepted by Omnisys in the fixed contract.

The work includes design, manufacture and test of the CSP device and the test focus of the behaviour of the cascade port. As the device is full custom, no "mass" production can be implemented, only few will be produced to test the concept.

4.3 Design of Omnisys full custom CSP

The design is based on a two sided PCB with 75 um track with and spacing, also using padless vias. The PCB is then 15x15 mm and 0.5 mm thick. Evaluation was performed early on regarding size of the carrier, and the conclusion was that the design used created the minimum parasitics for the chip to chip cascade port, with close to perfect length matching. The design has all "bumps" in a ring around the chip, except for the grounding, where 16 bumps are situated in the middle. The top of the chip is then "globbed", i.e. epoxy or silicon based material is applied for physical protection.
An alternative would be to have the bumps under the chip, but while the package size would be a bit smaller, the interconnect parasitics would increase. A PCB layout of the carrier is shown in Figure 4.2.

One of the major advantages with the package type is the possibility to include passive devices. This capability was used to put in single layer decoupling capacitors on the power supply rail, one in each chip corner, and on the cascade reference voltages, two on the input, two on the output and one on the ADC input.

4.4 Test set-up

One single test-board was designed and produced, but implementing two functions.

These are the cascade test set-up, using two CSP footprints, and one ADC feeding the chips with test data. In addition, there is a test set-up with socket, using one QFP144 corchip to feed signals to the chip, and one more QFP144 corchip to test the cascade output functions. Only limited speed tests are possible with this set-up due to the socket.

The plan is to just compare the behaviour of the chip sets under different conditions, not to find any formal highest operating speed. The chip set is clocked via a clock buffer driven by a CW synthesized source for both cases, and a different CW source is used to provide a test input to the ADC. The test procedure is to find maximum operating speed by visual inspection of the readout correlator data, while optimising bias references etc.

These test results come from the previous stage in the project, the report named "The Correlator Chip Set High Speed Demonstrator".

The purpose of this system is to evaluate highest possible clock speed of the correlator chip set by using a naked die, chip-on-board implementation.

The clock and data sources were pure synthesized CW signals, ac coupled, and the squaring of the clock signal and differentiation was left to the clock buffer in the block diagram. Standard microwave sources from HP were used.
The test results is shown below in Table 4.1.

<table>
<thead>
<tr>
<th>Source</th>
<th>Chip</th>
<th>Raw clock</th>
<th>CC clock</th>
<th>Bandwidth</th>
</tr>
</thead>
<tbody>
<tr>
<td>CW signal</td>
<td>Real Board 1</td>
<td>1200 MHz</td>
<td>300 MHz</td>
<td>600 MHz</td>
</tr>
<tr>
<td>Complex Board 1, 3.75 V</td>
<td>750 MHz</td>
<td>375 MHz</td>
<td>750 MHz</td>
<td></td>
</tr>
<tr>
<td>Real Board 2, 3.75 V</td>
<td>1500 MHz</td>
<td>375 MHz</td>
<td>750 MHz</td>
<td></td>
</tr>
</tbody>
</table>

As the maximum clock rates were a bit low, another board with just one real circuit was also tested to get some idea about performance spread from chip to chip.

4.5 Test results with CSP

The CSP tests use the set-up shown in Figure 4.3, also shown in Figure 4.4. The set-up consist of a clock receiver, a real ADC and two cascaded CSP chips.
4.6 Test result comparison

In table 4.2, some relevant test results are compared. In the first case, the naked die version was faster, while the roles were changed looking at the case with higher supply voltage. The result varies from chip to chip in both cases, but the conclusion could be that they are comparable.

In the last case, the CSP cascade is slower than for the case with naked die, but the operating temperature is much higher for the CSP case. Simple cooling was provided showing an immediate improvement. The conclusion could be that the CSP cascade is a bit slower than naked die cascade, but issues like chip to chip spread and efficient cooling also comes into the picture.

<table>
<thead>
<tr>
<th>Source</th>
<th>Chip</th>
<th>Raw clock</th>
<th>Supply</th>
</tr>
</thead>
<tbody>
<tr>
<td>CW signal</td>
<td>Naked chip 0</td>
<td>1100 MHz</td>
<td>3.3 V</td>
</tr>
<tr>
<td>CW signal</td>
<td>CSP chip 0</td>
<td>920 MHz</td>
<td>3.3 V</td>
</tr>
<tr>
<td>CW signal</td>
<td>Naked chip 0</td>
<td>1200 MHz</td>
<td>3.75 V</td>
</tr>
<tr>
<td>CW signal</td>
<td>CSP chip 0</td>
<td>1310 MHz</td>
<td>3.75 V</td>
</tr>
</tbody>
</table>

TABLE 4.2 Comparison

4.7 Summary and conclusion

The design of the Chip Scale Packages gave the following results:

1. The PCB area went from 25x25 mm down to 15x15 mm, a reduction of 64%.
2. The speed result are that the CSP falls somewhere between naked die and QFP

Regarding area, it is probably possible to go down to some 13x13 mm with the same type of packaging, or at least 14x14 mm. For further reduction, flip chip mounting is necessary, but 10x10 mm seems possible. The package design seems quite straightforward, but "bumping" and "globbing" needs considerable testing and process tuning. Bumping is the attachment of the solder bumps to the package, while globbing is the cover of the chips by some kind of epoxy or silicon based compound.

Regarding speed, it seems that the difference in speed between Naked Die and CSP can to a large degree depend on thermal considerations. The CSP gets very hot, especially when operated at 3.75 V, and thermal enhancements of package as well as circuit board should be considered before production.
5 Three Level Digitizer

5.1 Digitizer Design

5.1.1 Introduction

This section will describe the specification, development methods, principal function and test results of the complex quantizer used by the correlator chip set.

Critical items

- Speed is the overall most important design goal
- High speed analog inputs
- Analog reference inputs
- High speed digital outputs
- Pinout to ease PCB layout and improve signal integrity

Because of the rather high frequency the chip design is primarily speed-optimized. Power consumption could have been lowered a bit without falling out of speed specifications, but this would hardly have made any difference on the whole spectrometer power consumption. Now the chip will instead have better speed margins.

![FIGURE 5.1 Complex digitizer layout](image)

The analog high speed inputs are terminated internally in order to avoid reflections caused by bad input impedance matching.

The analog reference inputs are internally decoupled in order to minimize coupling between high speed signals and references.

The high speed digital outputs are differential in order to increase the signal level and to simplify quantizer-
to-correlator interface trimming. In a previous design where single ended digital signals were used, trimming of the decision level in the correlator high speed receiver proved to be tricky. This was because the signal offset level depends on both quantizer supply voltage and operating temperature.

The pinout is arranged to separate the different interfaces as much as possible. In particular the two analog input channels are separated from each other as well as from the digital outputs.

### 5.1.2 Performance

Simulated performance figures for the complex quantizer together with input requirement are given in Table 5.1.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Simulated performance</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Min supply voltage</td>
<td>2.2 V</td>
<td>2.5 V</td>
</tr>
<tr>
<td>Current consumption</td>
<td>75 mA</td>
<td>TBD</td>
</tr>
<tr>
<td>Max supply voltage</td>
<td>2.8 V</td>
<td>-</td>
</tr>
<tr>
<td>Output rise/fall time</td>
<td>200 ps</td>
<td>-</td>
</tr>
<tr>
<td>Output swing</td>
<td>&gt; 350 mV differential</td>
<td>differential</td>
</tr>
<tr>
<td>Input frequency</td>
<td>2 GHz</td>
<td>750 MHz</td>
</tr>
<tr>
<td>Input dynamic range</td>
<td>1700 mV to Vcc</td>
<td>TBD ± 250 mV</td>
</tr>
<tr>
<td>Clock frequency</td>
<td>4 GHz</td>
<td>2.2 GHz</td>
</tr>
<tr>
<td>Clock swing max.</td>
<td>800 mV differential p-p</td>
<td>differential</td>
</tr>
<tr>
<td>Clock swing min.</td>
<td>2 mV differential p-p</td>
<td>differential</td>
</tr>
<tr>
<td>Clock offset range</td>
<td>1700 mV to Vcc-200 mV</td>
<td>-</td>
</tr>
<tr>
<td>Select signal high min.</td>
<td>Vcc-0.1 V</td>
<td>-</td>
</tr>
<tr>
<td>Select signal low max.</td>
<td>Vcc-0.5 V</td>
<td>-</td>
</tr>
<tr>
<td>S1,S2)</td>
<td>Clock division factor = 8, 4, 2, 1</td>
<td>-</td>
</tr>
<tr>
<td>Input sensitivity</td>
<td>100 µV</td>
<td>1 mV</td>
</tr>
<tr>
<td>Layout</td>
<td>780 x 1200 µm²</td>
<td>-</td>
</tr>
</tbody>
</table>

### 5.1.3 Technology and Methods

The quantizer has been processed by Ericsson Components AB using their P71 bipolar process, revision r2b. The vast majority of transistors used are the 0.6 x 1.5 µm NPNs, with a turnover frequency of about 24 GHz.

The design has been simulated partly and as a whole using Cadence. Layout has been done using Cadence design system. The design is solely optimized for speed.

### 5.1.4 Functional description

The complex quantizer is a dual channel 1.5-bit analog-to-digital converter intended to be used with a complex correlator in a spectrometer. The architecture of the complex quantizer is shown in Figure 5.2. There are two independent data signal chains, I and Q, with time de-multiplexing factor of two. Each of these data chains has one signal input and two reference inputs.

The analogue signal enters on the input pin on the pre-amplifiers. These amplifiers are used for increased precision, transforming the indecision of the sampling flip-flop to an acceptable level. The sampling circuit consists of a simple flip-flop giving a maximum set-up time for the following de-multiplexing stages.
The de-multiplexing stages performing the 2:1 time demultiplexing consist of a number of latches with a peculiar clock configuration. The output buffer is a pure differential driver, used for both data and clock signals.

The clock signal enters the chip differentially and is, after a simple pre-amplifier stage, supplied to a prescaler. This block is programmable by setting the two control bits in one out of four states. The selectable divide ratios are 1, 2, 4 and 8. The internal clock signal is fed to the samplers and via a divide by two circuit to the de-multiplexor.

Finally the clock is presented to the outside by a, with the data path identical, differential buffer.

In the picture below, the layout of the chip is presented. On the left the quadrature encoded I- and Q signal inputs and the four reference signals are seen, as well as the differential input clock. On the right side of the chip all differential outputs including the clock are seen. Ground is input on each side of the differential input clock, and Vcc in the upper left corner.

### 5.2 Digitizer Testing

#### 5.2.1 Digitizer Test setup

Figure 5.3 shows the quantizer test board. Power is connected to the right, clock is connected on the upper side of the PCB. On the lower edge of the PCB I- and Q signals are connected. Reference levels are adjusted using trimming potentiometers.
The actual chip dimensions are 1.2 by 0.8 mm. The metal frame around the chip (along the picture frame) is provided for grounding oscilloscope probes. The vias, which are a bit closer to the chip, are the actual probe points. The picture also shows that the reference decoupling capacitors (size 0402) are rather far away from the chip. If single layer capacitors were used, they could be placed on the bonding pads.

5.2.2 DC characteristics

5.2.2.1 Power consumption

Measurements have proved the current consumption being independent of clock frequency and input signals and the total power consumption is between 220-270 mW depending on supply rail.

5.2.3 Digital threshold levels

The only digital signals on the quantizer are the clock divisor select signals S1 and S2. Table 5.2 and Table 5.3 shows the threshold levels for these control signals. As can be noted, the thresholds are only some 0.2-0.3V below the supply voltage. The indecision for these signals are some 20-40 mV.

<table>
<thead>
<tr>
<th>Signal</th>
<th>Low threshold (V)</th>
<th>High threshold (V)</th>
</tr>
</thead>
<tbody>
<tr>
<td>S1</td>
<td>1.92</td>
<td>1.96</td>
</tr>
<tr>
<td>S2</td>
<td>1.92</td>
<td>1.96</td>
</tr>
</tbody>
</table>

5.2.4 Comparator threshold versus reference levels

All measurements below have been performed at room temperature, 2.50V supply voltage, 1GHz sampling clock frequency using a clock division factor of 8.
The conclusion from these tests are that the basic operation is proven.

To test the implications of the indecision and offset levels, the chip set must be operated in a spectrometer. The test here shows that the levels are low, and implications should be removed by the spectrometer signal processing.

This was later also proven by the lab testing of the demonstrator, as described in section 8 of this report.
6 Correlator chip(s)

6.1 Correlator Chip Design

6.1.1 Introduction

This section describes the design, layout and usage of the 128-channel complex correlator chip and a 1024 channel chip. Design concepts are identical in both chips, the main difference is the number of channels. The 128 channel chip was submitted to foundry in February 2001. The 1024 channel design was submitted to foundry in March of 2002, and delivered in February 2003. This delay has been the main cause of the changes in the overall schedule and planning.

This correlator chip can be used in several ways:

- Complex (IQ) auto-correlation, using a time division multiplex factor of two
- Real auto-correlation, using a time division multiplex factor of four
- Dual channel real auto-correlation, using a time division multiplex factor of two
- Real cross-correlation, using a time division multiplex factor of two

However, this section does only describe how to use it when computing complex auto-correlation.

Critical items

- Speed is the overall most important design goal
- Power consumption
- Differential high speed inputs
- Integrator length
- Data readout scheme
- Pinout to ease PCB layout

Because of the rather high frequency the chip design is primarily speed-optimized. Power consumption could indeed have been lowered a bit without falling out of speed specifications, but this rather small chip was designed to be as fast as possible.

The high speed digital inputs from the quantizer are differential in order to increase these signal levels and to simplify quantizer-to-correlator interface trimming. In a previous design where single ended digital signals were used, trimming of the decision level in the correlator high speed receiver proved to be tricky. This was because the signal offset level depends on both quantizer supply voltage and operating temperature.

The integrator length and the clock frequency determines maximum integration time. The number of non-readable bits (prescaler bits) in the integrator can set the signal noise floor higher, if the number of prescaler bits is too large and the input signal noise level is low.

The data readout scheme determines how many I/O-pads that are required. A simple serial interface has been chosen due to the limited number of pins this requires, and because this will significantly simplify PCB layout compared to a parallel interface.

The pinout is arranged to separate the different interfaces as much as possible. In particular the high speed inputs are separated from the digital control and readout signals.

6.1.2 Technology and methods

The correlator is designed for ST Microelectronics HCMOS7 process, version 3.0 (0.25µm CMOS process). Cadence design tools (Composer, Virtuoso and Analog Artist) have been used throughout the whole design process. All design blocks have been simulated in SpectreS. Some blocks have due to complexity reasons only been simulated partially.
6.1.3 Functional description

Figure 6.1 displays the principle of complex auto-correlation. The quadrature signals I and Q are forwarded to the multipliers, both delayed and non-delayed. The result is then integrated in the summation blocks.

In this correlator chip I and Q data is time multiplexed by a factor of two, in order to improve data throughput. This makes the correlation blocks a bit more intricate, but the principle remains the same.

Some details are shown the following subsections. The fine tuning of e.g. clocking and internal data buffering are detailed in the design report.

6.1.4 Inputs from quantizer

The previous correlator chip used a differential input for the clock and pseudo-ECL inputs for quantizer data. This interface required some trimming of the reference level used by the pseudo-ECL inputs and was somewhat sensitive to temperature and supply voltage variations. Due to these experiences, as well as need for higher clock rate, a fully differential interface was implemented between the quantizer and the correlator chip.

The input pads used for the quantizer interface are customized standard analog pads. In these analog pads some metal has been removed to decrease parasitic capacitance, while retaining full protection circuitry. This is also compliant with the design rules. Both clock and data inputs use the same differential amplifier/comparator, shown in Figure 6.2.
It is very important that data and clock from the quantizer are equally delayed all the way from the quantizer to the first internal buffering block.

### 6.1.5 Digital I/O

All digital I/O has been designed using ST Microelectronics standard I/O-cells. All digital inputs are schmitt-triggered to improve noise immunity. Digital I/O is used for serial data readout and correlation control.

### 6.1.6 Power distribution

The chip has separate power pads for input buffers, correlator core and digital I/O in order to minimize noise in the input circuitry.

The local power lines are designed to have less current density than the design rules allow at maximum chip temperature. Since the process has as many as six metal layers, two metal layers have been dedicated to global power distribution in order to keep the voltage drop across the chip as low as possible.

Local power decoupling capacitors are inserted close to all significant power consumers, i.e. near clock drivers, data buffers and multipliers. These capacitors and the asynchronous nature of the chip will make sure the supply current spikes are spread in time, thus keeping power supply noise low.

### 6.1.7 Correlation

The correlation block is a 1.5 bit multiplier. Since the input signals are limited to values -1, 0 and +1 the result is also limited to -1, 0 and +1. This makes the multiplier circuit extremely simple.

![Multiplier schematic](image)

**FIGURE 6.3 Multiplier schematic**

The multiplier is optimized for speed, as it runs at full clock speed. Since the “height” of the multiplier layout cell determines the length of the correlator core, the “height” is squeezed as much as possible.

Figure 6.3 shows the multiplier schematic. As can be seen, it consists of only 9 transistors plus buffers. When the result of the multiplication is positive a pulse is forwarded to the positive integrator and when the result is negative a pulse is forwarded to the negative integrator. A zero result will cause no output pulse.

### 6.1.8 Integration

The integrator accumulates auto-correlation results. The integrator is divided into two sections: prescaler and readable integrator. The prescaler is optimized for speed and is running at full clock speed. The readable integrator is on the other hand optimized for area and is only running at a few MHz at most.

The total number of bits in the integrator is determined by the maximum integration time required and the clock frequency. The number of readable bits is determined by the noise level in the input signal. 31 integrator bits, of which 23 can be read, and a clock frequency of 1GHz yields a maximum integration time of more than one second.
Since data from the correlation block is time multiplexed by a factor of two, a lot of area can be saved by demultiplexing (adding) the data in the integrator, instead of demultiplexing data when reading the data from the integrator. This demultiplexing is handled by the Clock joining block.

Figure 6.4 shows how time multiplexing and positive/negative data is handled in the integrator. The two multipliers to the left in the picture generates the time multiplexed correlation data, which is divided by the prescaler and integrated in the readable integrator.

6.1.9 Prescaler

The prescaler is an 8-bit high speed ripple counter made up of semi-static T-type flip-flops. Only minor changes has been made since the last correlator chip project.

Figure 6.5 shows the principal schematic of the semi-static T-type flip-flop. A high pulse is generated on the output during every second pulse on the input ($\phi$). One important feature of this cell is that the logic state is stable when the input signal is low. This will prevent oscillations that would occur in a fully dynamic cell when no input clock is present.

As both input and output signals from the flip-flop are pulses, it is very important that the output pulse is slightly wider than the input pulse. If this was not the case pulses might vanish in the prescaler.

6.1.10 Readable integrator

The readable integrator is a 23-bit low speed ripple counter consisting of static T-type flip-flops. The counter can be reset to zero by holding the /reset signal low.

There is a multiplexed output in this ripple counter, which is used when data is read out. This allows several integrators to be read out using a single parallel bus.

6.1.11 Data readout

Since the chip is more or less limited by IO there is a need to minimize the number of pads. A good way of minimizing the number of IOs is to use a serial bus instead of a parallel bus. The previous correlator chip utilized a total number of 25 data and control signals. This number has been cut down to six pads, of which three are used for debugging.

The serial style of reading out data has several advantages:
• System level design, when only a few signals may need routing between PCBs or boxes
• EMC aspects, when only a few signals need filtering/shielding
• More data bits per integrator don’t require more pads

The only drawback when using a serial interface is the data transfer time, which needs to be investigated if the number of correlation lags is increased. The total time for reading out all correlation data, \( \tau \), can be found by using the formula below:

\[
\tau = \frac{(2 \cdot \text{channels} + 6) \cdot 24}{\text{bitrate}}
\]

In the formula above 2 is the number of data values per correlation lag, 6 is the number of monitor values (including the dummy monitor) and 24 is the number of bits per data value.

As an example, all data from this 128-channel (128 correlation lags) can be read in about 0.63 milliseconds, when using a 10MHz serial clock.

![Figure 6.6](image.png)

**FIGURE 6.6** 128 channel Correlator chip. Die size is 2500 x 3000 um.

### 6.1.12 128 channel implementation

The correlator core area is 25% smaller than a proportional scaling of the previous chip design; 3.15mm\(^2\) vs. 33.6mm\(^2\)/(4*2)=4.2mm\(^2\). 4 is the proportional area scaling factor and 2 is the ratio of channels in the previous chip relative to this. This area reduction has been possible thanks to the real-time time-demultiplexing of data. The serial data readout saves a lot of system level effort when several correlator chips are used in one instrument.

There are more readable bits in the integrators. This has been possible thanks to serial data readout and real-time time-demultiplexing of data.

The clock speed is improved by 80% compared to specification and is 20-30% faster than expected. Power consumption is as expected. Or, the other way around, the power consumption has been allowed to become a bit higher than absolute minimum in order to increase the clock frequency.
Table 6.1 displays a summary on chip design/simulation results vs. specifications.

Table 6.1 Comparison specification - simulation/design results

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
<th>Simulation/design result</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power consumption per channel and effective sampling frequency</td>
<td>1mW/GHz</td>
<td>~0.5mW/GHz @ 550MHz clock</td>
</tr>
<tr>
<td>Clock frequency</td>
<td>550MHz min.</td>
<td>~1GHz</td>
</tr>
<tr>
<td>Area, correlator core</td>
<td>-</td>
<td>3.15mm²</td>
</tr>
<tr>
<td>Area, with pads</td>
<td>-</td>
<td>7.5mm²</td>
</tr>
<tr>
<td>Number of channels</td>
<td>64</td>
<td>128, of which 64 can be disabled</td>
</tr>
</tbody>
</table>

6.1.13 1024 channel implementation

The correlator core area is 23% smaller than a proportional scaling of the previous generation chip design; 25.8mm² vs. 33.6mm²/4/4=33.6mm². Where 4 is the proportional area scaling factor and the ratio of channels in this chip relative to the previous generation chip. This area reduction has been possible thanks to the real-time time-demultiplexing of data.

The serial data readout saves a lot of system level effort when several correlator chips are used in one instrument. The auxiliary control register may even further ease the system design.

The chip can dynamically be configured to have 64, 128, 256, 384, 512, 768 or 1024 channels. This may be useful for conserving power when not all 1024 channels are needed at all times.

The clock speed is improved by 80% compared to specification and is 20-30% faster than expected. Power consumption is as expected. Or, the other way around, the power consumption has been allowed to become a bit higher than absolute minimum in order to increase the clock frequency.
Table 6.2 displays a summary on chip design/simulation results vs. specifications.

**TABLE 6.2 Comparison specification - simulation/design results**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
<th>Simulation/design result</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power consumption per channel and effective sampling frequency</td>
<td>1mW/GHz</td>
<td>~0.5mW/GHz @ 550MHz clock</td>
</tr>
<tr>
<td>Clock frequency</td>
<td>550MHz min.</td>
<td>~1GHz</td>
</tr>
<tr>
<td>Area, correlator core</td>
<td>-</td>
<td>25.8mm²</td>
</tr>
<tr>
<td>Area, with pads</td>
<td>-</td>
<td>35mm²</td>
</tr>
<tr>
<td>Number of channels</td>
<td>1024</td>
<td>64, 128, 256, 384, 512, 768 or 1024, depending on enable signals</td>
</tr>
</tbody>
</table>

### 6.2 Correlator Chip Testing

#### 6.2.1 Test setup

Figure 6.8 shows the correlator chip test board for the 1024 channel MCM. A similar board was used for the 128 channel MCM.

The test results below is from the 128 channel MCM testing. The 1024 channel tests were completely consistent with these results.

![Correlator chip test board](image)

**FIGURE 6.8 Correlator chip test board**

#### 6.2.2 Quiescent power consumption

The correlator chip has separate supply lines for the input stage (high-speed differential receivers), the correlator core and low-speed digital I/O pads, which permits separate power consumption monitoring (correlator core and digital I/O supply are connected to a common pad on the correlator module and have to be monitored together).

The input stage power consumption is dominated by static currents in the differential amplifiers and is hardly affected by changes in data and sampling frequency.

The correlator core is dominated by dynamic power consumption in data buffers and in integrators. Thus it is heavily dependent on both clock frequency and data contents. When data is read out from the chip, some additional static currents paths are enabled, increasing the power consumption slightly.
6.2.3 Correlator AC power consumption

Figure 6.9 shows correlator power consumption versus sampling frequency. Furthermore, power consumption is displayed for three different input data streams:

- No data (I=Q=0 for all samples)
- Maximum data level (I=+1 or -1, Q=+1 or -1 for all samples)
- Normal data (white noise), (I=0 for 50% of all samples, Q=0 for 50% of all samples)

As can be seen, the power consumption does not fall to 0mW at 0 sampling frequency. This is mainly caused by static current consumption (about 10mA) in the differential receivers. The correlator core/digital I/O circuitry adds another 2mA in static power consumption. For a full correlator module it should be noted that the quantizer adds another 80mA (200mW).

The power consumption could be said to be roughly:

\[ P = 30 \text{ mW} + 1 \text{ mW} / \text{channel} / \text{processed GHz}, \]

or as often given

\[ P = 30 \text{ mW} + 0.5 \text{ mW} / \text{channel} / \text{GHz sampling rate} \]

In addition, there is a small deviation from a straight line in both plots around 1600 MHz. This is the maximum clock rate in this set-up, higher clock rate was later achieved with better cooling of the test board.

6.2.4 Maximum correlation data rate

The maximum correlation data rate (and thus the sampling frequency) depends on the supply voltage. The chip seems to gain performance with rising supply voltage. However, ST Microelectronics process specifications suggests that the top performance should be at about 2.5V. Figure 6.10 shows how the
maximum sampling frequency depends on the supply voltage and input data.

\[ \text{FIGURE 6.10 Maximum clock rate for correlation} \]

It is interesting that the curves for a CW-signal and for noise are that different in shape. All speed measurements have been performed with 1024 channels enabled. As the maximum clock rate is inversely proportional to the physical temperature of the die, it is possible to run the chip a bit faster if fewer channels than 1024 are enabled, as less heat is produced (and if the set-up is the same).

6.2.5 Data read-out dynamic power consumption

At 2.56V the correlator core and digital I/O buffers requires a total of about 11mA/28mW (depends a bit on correlation data) when reading out data using a 2MHz clock in single read-out-interface mode. Add to this 10mA/26mW which input stage requires. This yield a total chip power consumption of 54mW during data read-out. Note that the input stage may actually be powered down during read-out and stand-by, since the input circuitry has separate supply pads.

6.2.6 Results

Table 6.4 and 6.4 displays a summary on chip measurements and design/simulation results vs. specifications.

**TABLE 6.3** Comparison 128 channel chip specification, simulation/design and measurements

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
<th>Simulation/design result</th>
<th>Measured</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power consumption per channel and effective sampling frequency</td>
<td>1mW/GHz</td>
<td>~0.5mW/GHz @ 1.1GHz complex sampling clock, 2.5V</td>
<td>0.64mW/GHz @ 1.1GHz complex sampling clock, 2.52V</td>
</tr>
<tr>
<td>Clock frequency</td>
<td>550MHz min.</td>
<td>~1GHz</td>
<td>&gt;=1GHz</td>
</tr>
<tr>
<td>Area, correlator core</td>
<td>-</td>
<td>3.15mm²</td>
<td>-</td>
</tr>
<tr>
<td>Area, with pads</td>
<td>-</td>
<td>7.5mm²</td>
<td>-</td>
</tr>
<tr>
<td>Number of channels</td>
<td>1024</td>
<td>64 or 128</td>
<td>64 or 128</td>
</tr>
</tbody>
</table>

**TABLE 6.4** Comparison 1024 channel chip specification, simulation/design and measurements

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
<th>Simulation/design result</th>
<th>Measured</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power consumption per channel and effective sampling frequency</td>
<td>1mW/GHz</td>
<td>~0.3mW/GHz @ 1.1GHz complex sampling clock, 2.5V</td>
<td>0.51mW/GHz @ 1.1GHz complex sampling clock, 2.51V</td>
</tr>
<tr>
<td>Clock frequency</td>
<td>550MHz min.</td>
<td>~1GHz</td>
<td>&gt;=800MHz</td>
</tr>
<tr>
<td>Area, correlator core</td>
<td>-</td>
<td>25.8mm²</td>
<td>-</td>
</tr>
</tbody>
</table>
TABLE 6.4 Comparison 1024 channel chip specification, simulation/design and measurements

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
<th>Simulation/design result</th>
<th>Measured</th>
</tr>
</thead>
<tbody>
<tr>
<td>Area, with pads</td>
<td>-</td>
<td>35mm²</td>
<td>-</td>
</tr>
<tr>
<td>Number of channels</td>
<td>1024</td>
<td>64, 128, 256, 384, 512, 768 or 1024</td>
<td>64, 128, 256, 384, 512, 768 or 1024</td>
</tr>
</tbody>
</table>

6.2.7 Conclusions

The correlator chip seems to work up to about 1.6GHz complex sampling frequency at nominal supply voltage. The measured maximum frequency and power consumption matches the results of the simulations quite well. The input bandwidth and power consumption is well within the specifications.

The small bug in the read-out control circuitry is of course a bit annoying but is not in any way serious. Another thing worth noticing when building an instrument with this chip is that the read-out interface has become a bit slow; it might take about 3 ms to read out all data from the chip.
7 Radiation tests

7.1 Device under test

The primary devices under test were the full custom bipolar complex quantizer chip (ASCB001B) and the full custom CMOS 128-channel complex auto correlator chip (ASCB002B). Secondary devices under test were Analog Devices’ ADF4113BRU PLL frequency synthesizer and Linear Technology’s LT1660CGN octal DAC.

Figure 7.1 shows the test board which, was used for the radiation test.

![Radiation test board.](image)

The areas marked on the board are:
1. Local oscillator (PLL, VCO and crystal oscillator)
2. IQ-mixer. (These circuits were removed from the board during the radiation test)
3. Correlator chip
4. Quantizer chip
5. DAC for quantizer reference levels
6. Digital control and interface circuitry
7. Power supply

To allow for the desired monitoring, a number of current sense resistors were added to the board, which are not included in the figure.

The original plan was to irradiate only the correlator and quantizer module and the local oscillator. However, it proved to be better to irradiate the full board, to get a more reliable dose rate measure.

7.2 Test setup

The irradiation was performed at Sahlgrenska (University Hospital), using a cobalt-60 source calibrated for a dose rate of 412Rad/h, calculated to give about 30kRad over a 3-day test campaign.

Figure 7.2 shows a sketch of the test setup, where the cobalt-60 source radiates the device under test (DUT). A power supply and a CW signal generator provides the necessary signals to the board, while the data acquisition unit monitors and records voltages and currents. In addition a laptop computer was used for daily backup of the acquired data.
FIGURE 7.2 Test set-up block diagram.

Figure 7.3 shows the real test setup at Sahlgrenska, where the main parts are marked:

- Device under test
- Power supply, providing 5V to the test board
- Data acquisition unit
- CW signal generator, providing the quantizer with a 1GHz sampling clock
- Cobalt-60 radiation source, with a dose rate of 412Rad/h

FIGURE 7.3 Test set-up.

7.3 Monitored signals

The following signals were monitored by the data acquisition unit:

- supply voltages
- quantizer supply current
- correlator core and input circuitry supply currents
- PLL core and digital I/O supply currents
- VCO supply current
- frequency synthesizer feedback loop filter OPAMP supply current
- DAC, DAC reference and reference OPAMP supply current
- 7 digital outputs from the on-board micro controller
- ambient temperature
7.4 Test procedure
The on-board micro controller was programmed to repeatedly do the following tests:

- check the PLLs lock detect signal, by forcing it high and low
- check that the PLL doesn’t report successful locking outside the VCOs frequency range
- check that the PLL reports successful locking at the nominal LO frequency
- correlate one second each at 1GHz, 500MHz, 250MHz and 125MHz sampling frequency, using four different data patterns, checking that the resulting monitor and correlation data is correct
- correlate 95 seconds at 1GHz for each of three different data patterns, so the current consumption can be monitored

After the full 74 hours of irradiation (31kRad), the devices and instruments were moved back to Omnisys lab, where the failed micro controller was replaced and annealing was performed, with the same monitoring and software running as in the beginning of the irradiation period.

7.5 Results
In conclusion, the correlator MCM complied with specification after 31 kRAD radiation. For both the correlator chip (CMOS) and digitizer (Bipolar), the changes in power consumption was negligible.
8. The 6 GHz Spectrometer Demonstrator

8.1 Demonstrator Design

The spectrometer demonstrator is contained in a dual compartment aluminium box. It consists of three printed circuit boards; the intermediate frequency signal distribution board (IF), the quadrature mixing board (IQ) and the correlator board (CCM).

General test results:

- weight: 0.74kg
- supply voltage: single +5V
- power consumption: 6.2W
- input frequency range: 0.65GHz - 6.65 GHz (6GHz simultaneous bandwidth)
- frequency resolution: 13MHz/channel

These are between a factor of 3-10 better than specified for the demonstrator input specification, and there is even room for improvements.

As can be seen in Figure 8.2 and Figure 8.3, there is still much space in the box. The demonstrator can be fitted with a second IQ board and a redesigned CCM board with eight correlator chips, yielding a simultaneous processing bandwidth of 12GHz. The power consumption would then be about 10 W and the weight less than 1kg.

The demonstrator is based on the design shown in Figure 8.1.

![Demonstrator Design](image.png)

**FIGURE 8.1 Demonstrator design**

The design is based on a frequency multiplexed architecture, with four sub-bands covering 1.5 GHz each. The chip set implements time multiplexing, so that the complete spectrometer actually use both time and
frequency multiplexing.

The demonstrator consist mainly of one IF processing section, one IQ converter section and one Correlator Module section. This has been designed to be housed in one mechanical box of 170x110x30 mm size, with room for expansion to a 12 GHz spectrometer. This implies a duplication of most of the electronics.

Some of the main functions housed on the correlator PCB are:

- micro controller, crystal oscillator and interface circuits
- sampling clock generator (VCO, PLL, filter and voltage regulators)
- correlator support circuits (DACs and voltage regulators)
- correlator modules

Some of the main functions housed on the IF electronics are:

- local oscillators for the IQ mixers (VCOs, PLLs, filters and voltage regulators)
- IQ mixers (90-degree hybrids and mixers)
- amplifiers
8.2 Demonstrator Lab Testing

The demonstrator spectrometer has been tested on the lab bench.

For the spectrometric tests, a simulated noise source, combined with a CW signal generator has been used, as shown in Figure 8.4.

For the radiometric lab tests, the frequency coverage was tested, with example spectra shown in Figure 8.5. The jitter that can be seen is the mathematical $\cos(x)/x$ function, with the CW signal not focused in the centre of one channel, i.e. a feature that is not present for an astronomy or aeronomy spectra line, that have features wider than the maximum resolution of the spectrometer.
9 Radiometer Test Results

9.1 Introduction

The demonstration spectrometer has been tested in parallel with an AOS in a 110 GHz radiometer set-up at the University of Bremen.

The microwave radiometer BRERAM (BREmen Radiometer for Atmospheric Measurements) was developed for monitoring the vertical profiles of stratospheric ozone over Bremen.

Despite its small concentration, the atmospheric trace gas ozone (O3) is an important component of the atmosphere. On the one hand ozone absorbs the UV-B radiation which is harmful for the biosphere. On the other hand it contributes to the energy budget of the planet Earth, and determines the temperature structure of the stratosphere.

A microwave Radiometer (MR) is well suited to continuously monitor stratospheric composition since MR offer the possibility to measure ozone profiles continuously, day and night, and are only little affected by meteorological conditions. Furthermore a MR can be accurately calibrated by using reference radiators, so-called “Black Bodies” at various temperatures.

The output data has been compared by both Omnisys and a research group at Bremen. A short description of the test set-up and the results follow.

![BRERAM radiometer](image)

**FIGURE 9.1 BRERAM radiometer.**

9.2 Radiometer overview

The radiometer system consists of a quasi-optical processing subsystem, followed by a first downconversion stage. These two functions translate the sky signal of 110.8 GHz down to an intermediate frequency, centred around 8 GHz. This is often described as the “front-end” of a radiometer.

After this, a further downconversion follows, complemented with amplifiers, before AOS (Acousto Optical Spectrometer) signal processing. This is the back-end of the radiometer.

To operate the front-end and back-end, there is a need for a computer, power supplies and some additional control and telemetry electronics.
The complete assembly, can be seen in Figure 9.1.

9.3 Front-end details

The atmospheric signal enters the laboratory through a Styrofoam window which is transparent for microwaves. The first element in the front-end is a rotatable mirror by which the observation angle can be varied over an elevation range from 15 to 45 degrees. Measurements are performed in the total power mode, i.e. the mirror points in regular intervals at hot and cold calibration loads (Black Bodies), and under a preset angle at the sky. The calibration loads consist of microwave absorber material which can be considered as a black body emitter in the microwave region of the spectrum. The hot load is at room temperature (about 296K and the cold load is submerged into liquid Nitrogen with a temperature of about 77K.

Next we have the quasi optics; the signal beam is linearly polarized by a wire grid. The following elliptical mirrors are focussing the beam through all quasi optical elements to the horn antenna of the first mixer at 110GHz. In addition the optics contains an interferometer (Martin Puplett interferometer) used as single side band filter to suppress the unwanted image side band. Furthermore a path length modulator is used to reduce standing waves between the horn antenna and all quasi optical elements.

A rather large technical problem arises due to multiple reflections of the electromagnetic wave inside the quasi optics: Parallel plane surfaces will form a Fabry-Perot-Interferometer, which leads to a modulation of the pass band. The suppression of such undesired effects is done by the so-called path length modulator. The path length modulator (PLM) consists of a wire grid where the incoming linear polarized beam is totally reflected and directed on to a rooftop mirror which turns the polarization by 90 degrees. The reflected beam will transmit the grid and leave the PLM through the output port. The rooftop mirror is periodically moved back and forth, this will change the pathlength of the whole quasi optics, and consequently also change the
phase of the earlier mentioned modulation, which will smear out the baseline effects. This has been proven effective of reducing the ripple, but not eliminating them, and further ripple reduction is performed in the post processing of the AOS output.

![Diagram of quasi optical system](image)

**FIGURE 9.3 Quasi optical system.**

Finally the beam is focused into the horn antenna of the 110 GHz Mixer. The 110 GHz Mixer is a conventional Schottky diode mixer where the received radiation is mixed with a fixed frequency of the local oscillator at 118.836 GHz to generate the first intermediate frequency band with a center frequency of 8 GHz.

The complete radiometer set-up was developed by a rather limited budget, but has proven to produce valuable scientific results.

### 9.4 Back-end and ACS set-up

After the 8 GHz to 995 MHz translations stage in the back-end, as can be seen in Figure 9.1, a directional coupler was inserted in the radiometer. This enabled the operation of two spectrometers in parallel, the AOS and the ACS demonstrator developed in this project.

![Diagram of ACS test set-up](image)

**FIGURE 9.4 ACS test set-up.**

One amplifier was also introduced at the coupler output, to function as buffer, as well as providing 12 dB amplification to compensate for the directional coupler loss. The set-up is shown in Figure 9.4. During the first test session, a 1 dB step attenuator was also used, but for the second test session, as it was considered defective, it was removed.
It should be noted that the AOS set-up has been used and debugged for several years, while the ACS system integration is more ad-hoc. The main difference between the two spectrometers is that the ACS has about 13 MHz resolution, while the AOS has about 1 MHz.

9.5 Test results, analyses and discussion

The ACS was operated during the first test session as a piggy-back during normal observations for two months. In addition, some complementary tests were made several months later at a second test session. Standard practical problems were the operation as well as the control and data processing of the output data, as two different computers was used. This was with software developed at several years apart, by different organisations, processing data from two different types of spectrometers. The results still proved the function and performance of the ACS, but some debugging of the set-up was necessary.

![Figure 9.5 Spectra taken against a reference load. The frequency axis is not the sky frequency.](image)

In Figure 9.5, the raw spectra from observing the calibration load are shown, and in Figure 9.6 and 9.7, sky spectra with the ozone line are displayed. The ACS spectra are shown without any post processing, while the AOS spectra are convoluted with the response function of the ACS. The basic response of the ACS is a sinc function, and it effectively reduces the resolution of the AOS spectra from 1 MHz down to 7 MHz.

The real test of spectrometers are linearity and overall shape of the processed spectra. The linearity can be tested in the lab, as shown in an earlier chapter of this report, while the shape is best tested with a true spectrum. Observation of a spectrum also shows linearity and offset type of effects.

The plots show results from two different data sets, taken 15 minutes apart, resulting in a 17 K difference between the sets. In this plot, we can see that there is no offset between the AOS and ACS spectra. Furthermore, we can see that there is neither a linearity deviation, nor an overall shape disagreement.
FIGURE 9.6 Two sets of AOS and ACS spectra. Frequency axis is on the sky and GHz. Four spectra are shown, two ACS spectra and two AOS spectra. On the top, we have the AOS plot in blue and the ACS plot in red. On the bottom, we have the AOS plot in light blue and the ACS plot in green.

FIGURE 9.7 Another two sets of AOS and ACS spectra. Frequency axis is on the sky and GHz. Four spectra are shown, two ACS spectra and two AOS spectra. On the top, we have the AOS plot in blue and the ACS plot in green. On the bottom, we have the AOS plot in light blue and the ACS plot in red.
We have a number of observations from these spectra. These are primarily:

- the overall shape is very similar for the two spectrometers, i.e. both the peak and the slope over the spectra
- the linearity agrees
- there is no, or very little off-set between the AOS and ACS signal spectra
- a large interference peak in both AOS and ACS spectra close to 111.1 GHz

The large peak originates from one commercial RF transmitter in the Bremen area.

However, there are also a few deviations. These can or iginate from either the AOS or the ACS, but as the AOS is an operational instrument and the ACS is an early prototype in an ad-hoc set-up, it is expected that the ACS cause these deviations. These are:

- the response to the peak is different
- we have noted a small offset of around 1K between some ACS and AOS spectra (see lower part of fig. 9.5)
- we have a peak at 110.6 GHz in the ACS spectra but not in the AOS one.

Possibly, the fact of having a single converter (quantiser) for the whole spectrum could affect sensitivity or introduce a slight offset, when this quantiser is saturated by the presence of a strong interferer.

The left peak is caused by the ACS IQ mixer topology used in this particular ACS, used to translate the IF input signal down to DC baseband for the correlator to process. The LO for the IQ mixer is at 1.5 GHz (translated through the IF system to 110.6 GHz sky frequency) and the bump is the result of low frequency EMC disturbance.

In the set-up, the DC power supply wires were not shielded, and the RF environment was not controlled at all. This particular ACS is a low cost demonstrator and based on experience, one more design iteration would certainly remove this problem. A response on the IF-DC frequency is a common occurrence in the early prototyping phase of ACS spectrometers.

The small ripple effect (?) that can be seen in the spectra has not been fully explained. At the initial tests, Omnisys were informed that this could originate from quasi-optical ripple, but this explanation has later been questioned by Bremen. However some testing in this respect was performed. The LO was shifted in frequency and the bumps did not shift in the final spectra. This shows that they originate from outside the ACS. The same effect can be seen in Figure 9.6 and 9.7, with different data sets, but not in the calibration load spectra, Figure 9.5.

The most plausible explanation now is a ripple (reflections) in the temporary IF interface to the ACS, originating from a defective attenuator used in the set-up. This was not used for the calibration load tests that was taken at the second test session (Figure 9.5), and the ripple disappears in these spectra. The attenuator was determined defective after lab testing at Omnisys between the two sessions at Bremen.

The initial efforts to get the tests going were straightforward. However, the test procedures planned were not clear from both sides and there were also data format problems when comparing the AOS and ACS data. This made the interpretation harder of the unexpected deviations. After a few weeks, it was clear that there was a time extraction error in the Matlab code used and the wrong AOS and ACS spectra were compared.

Overall, the ACS showed a performance that was compliant with the scientist expectations, and it was clearly recognised that the small deviations shown could be expected in such a test set-up. The scientists at Bremen declared their interest in a high resolution ACS to complement the AOS, and asked for cost estimates for custom wide band implementations.

The performance issues seen in the comparison between the AOS and ACS are expected. The AOS have several years of debugging and improvements behind it, while the ACS had a few weeks of lab tests at Omnisys, and just a few hours of debugging of the set-up at Bremen.
10 Conclusion and future prospects

This report describes a spectrometer implemented in Multi Chip Module technology. The function and performance has been demonstrated in lab tests, as well as by operating a full demonstrator spectrometer in a ground based 110 GHz radiometer. There were two MCM’s produced, based on two different correlator chips.

The specification was 1 GHz bandwidth with 64 and 1024 spectral channels respectively, and with a power consumption of less than 1 mW/GHz/channel. The result is 1.7 GHz bandwidth, 128 and 1024 channels resolution, and 0.5 mW/GHz/channel power consumption.

Major items for spectrometers are of course bandwidth and system integration level, but for space applications, the power consumption is also vital. In this aspect, the chip set developed in this project is 23 times better than the competition.

To demonstrate the capabilities, a demonstrator has been designed and tested. The specification for the demonstrator has followed the Master/Marschal requirements, with 20 W power consumption and 10 kg mass. The demonstrator has shown that the performance can be realised with a system of less than 1 kg and less than 8 W power consumption. With flight development, this could be reduced to 4-5 W and 400 grams. The demonstrator has been proven to have a performance that match an AOS that is used by earth observation scientist at the University of Bremen.

Now, as a result from the development at Omnisys described in this report, a general conclusion is that autocorrelation spectrometers are very competitive with other type of spectrometers for space and ground based (sub)millimeter radiometry. The main advantages are: compact implementations, scalability and versatility in bandwidth and resolution, combined with potentially very high stability. There are no known, or proven disadvantages.

In terms of size and mass, the correlator is clearly much more compact than either the Chirp or the AOS, an optimised CTS being 2-3 times the size of a correlator, while an AOS is at least 10 times larger.

In terms of power consumption, the CTS is comparable to the ACS for narrow bandwidth, while the AOS consumes 2-4 times more than the ACS for wide bandwidth applications. The CTS can not compete for wide bandwidth applications, while the AOS is not competitive for high resolution use.

In terms of flexibility in bandwidth and resolution, the CTS and the AOS have very limited capabilities.

The ACS uses no special technologies and components, such as lasers, CCD's, Bragg Cell's or Chirp filters, with concerns regarding availability, radiation tolerance and other quality concerns. The only special technology is the full custom design of the chip set, while a $1000 Billion industry helping in the production line set-up. The NRE for the ASIC's are about $100-150 K.

There is a need for spectrometers for space based radiometers with between 4-10 GHz bandwidth in the next years to come. The best candidate to meet these requirements is the ACS, but additional development is needed. Omnisys has performed a design study, with the conclusion that it is clearly possible to develop a true single chip spectrometers with 4-6 GHz bandwidth and up 2000 channels. This would be a single chip spectrometer, including a large part of the IF processing. Based on this experience, it should be possible to achieve 10-15 GHz bandwidth within 3-5 years time, still with impressive size and power consumption figures.

The 4 GHz+ spectrometer chip would have a number of obvious applications. It would benefit most ground based and space borne aeronomy radiometers, as well as space science instruments.